



CMOS Chips for Sensing and Communication

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Message from the Guest Editors

This Special Issue encourages researchers to present theories, techniques, circuits, and systems of CMOS chips for radar/image sensing and wireless communication regarding emerging issues and challenges. The scope of this Special Issue focuses on, but is not limited to:

Imaging sensors: The development of image sensing with better performance and diverse functions, including high speed, high dynamic range, 3D imaging, low-light imaging and dynamic vision sensors, etc.

RF circuits: Building blocks at RF, mm-Wave and THz frequencies for receivers, transmitters, frequency synthesizers, transceivers, SoCs, and SiPs.

Wireless radar/communication transceivers: Circuit-level and system-architecture solutions for low-power, energy-efficient and high-performance wireless links, emerging broadband and phased-array systems, vehicle-to-everything (V2X), millimeter-wave and THz systems (radar, imaging, or communication).





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Message from the Editor-in-Chief

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